

Date:- 04 Oct, 2019

Data Sheet Issue:- P2

Tentative data Insulated Gate Bi-Polar Transistor Type T1000EC33G

Absolute Maximum Ratings

	VOLTAGE RATINGS	MAXIMUM LIMITS	UNITS
Vces	Collector – emitter voltage	3300	V
VDC link	Permanent DC voltage for 100 FIT failure rate.	1800	V
Vges	Peak gate – emitter voltage	±20	V

	RATINGS	MAXIMUM LIMITS	UNITS
IC(DC)	DC collector current, IGBT	1000	А
ICRM	Repetitive peak collector current, tp=1ms, IGBT	2000	А
IF(DC)	Continuous DC forward current, Diode	1000	А
IFRM	Repetitive peak forward current, tp=1ms, Diode	2000	А
IFSM	Peak non-repetitive surge $t_p=10ms$, $V_{RM}=60\%V_{RRM}$, Diode (Note 4)	6000	А
I _{FSM2}	Peak non-repetitive surge t _p =10ms, V _{RM} ≤10V, Diode (Note 4)	6600	А
Рмах	Maximum power dissipation, IGBT (Note 2)	6.4	kW
PD	Maximum power dissipation, Diode (Note 2)	4.05	kW
(di/dt) _{cr}	Critical diode di/dt (note 3)	2000	A/µs
Tj	Operating temperature range.	-40 to +125	°C
T _{stg}	Storage temperature range.	-40 to +125	°C

Notes: -

1) Unless otherwise indicated $T_j = 125^{\circ}C$.

2) $T_{sink} = 25^{\circ}C$, double side cooled.

3) Maximum commutation loop inductance 200nH.

4) Half-sinewave, 125°C T_j initial.

Characteristics

IGBT Characteristics

	PARAMETER	MIN	TYP	MAX	TEST CONDITIONS	UNITS
V _{CE(sat)} Collector – emitter satura		-	2.57	2.97	$I_C = 1000A, V_{GE} = 15V, T_j = 25^{\circ}C$	V
	Collector – enlitter saturation voltage	-	3.40	3.80	$I_C = 1000A, V_{GE} = 15V$	V
Vo	Threshold voltage	-	-	1.84	Current ren rev 222 40004	V
rs	Slope resistance	-	-	1.97	Current range: 333 – 1000A	mΩ
$V_{\text{GE(TH)}}$	Gate threshold voltage	-	5.3	-	$V_{CE} = V_{GE}, I_C = 85 \text{mA}$	V
ICES	Collector – emitter cut-off current		10	25	$V_{CE} = V_{CES}, V_{GE} = 0V$	mA
I _{GES}	Gate leakage current	-	-	±10	$V_{GE} = \pm 20V$	μA
Cies	Input capacitance	-	135	-	V_{CE} = 25V, V_{GE} = 0V, f = 1MHz	nF
t _{d(on)}	Turn-on delay time	-	1.7	-		μs
tr(V)	Rise time	-	1.8	-	I _C =1000A, V _{CE} =1800V, di/dt=2000A/μs	μs
Qg(on)	Turn-on gate charge	-	21	-	$V_{GE} = \pm 15V$, L _s =200nH	μC
Eon	Turn-on energy	-	2.6	-	$R_{G(ON)}$ = 2.2 Ω , $R_{G(OFF)}$ =15 Ω , C_{GE} =430nF	J
t _{d(off)}	Turn-off delay time	-	5.3	-	Integral diode used as freewheel diode	μs
t _f (I)	Fall time	-	1.5	-	(Note 3, 4 & 5)	μs
Qg(off)	Turn-off gate charge	-	13	-		μC
Eoff	Turn-off energy	-	2.7	-		J
lsc	Short circuit current	-	3000	-	V_{GE} +15V, V _{CC} =1800V, V _{CEmax} SV _{CES} , t_p S10µs	А

	Diode Characteristics							
	PARAMETER	MIN	TYP	MAX	TEST CONDITIONS	UNITS		
Vf	Forward voltage	-	2.66	2.95	IF = 1000A, T _j =25°C	V		
		-	3.0	3.3	IF = 1000A	V		
V ₀	Threshold voltage	-	-	1.71	Current range 333 - 1000A	V		
r _s	Slope resistance	-	-	1.59		mΩ		
Irm	Peak reverse recovery current	-	470	-	I _F = 1000A, V _{GE} = ±15V, di/dt=2000A/µs	А		
Qrr	Recovered charge	-	1040	-		μC		
trr	Reverse recovery time, 50% chord	-	1.7	-		μs		
Er	Reverse recovery energy	-	1.2	-		J		

Thermal Characteristics

	PARAMETER	MIN	TYP	MAX	TEST CONDITIONS	UNITS
R _{thJK}	Thermal resistance junction to sink, IGBT	-	-	15.6	Double side cooled	K/kW
		-	-	25.4	Collector side cooled	K/kW
		-	-	40.5	Emitter side cooled	K/kW
R _{thJK}	Thermal resistance junction to sink, Diode	-	-	24.7	Double side cooled	K/kW
		-	-	37.9	Cathode side cooled	K/kW
		-	-	70.8	Anode side cooled	K/kW
F	Mounting force	25	-	35	Note 2	kN
Wt	Weight	-	1.2	-		kg

Notes:-

es:-Unless otherwise indicated $T_j {=} 125^\circ C.$ Consult application note 2008AN01 for detailed mounting requirements C_{GE} is additional gate – emitter capacitance added to output of gate drive E_{on} integration time 15µs from 10% rising $I_{G.}$ E_{off} integration time 15µs from 90% falling V_{GE} .

4)

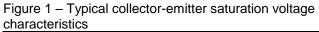
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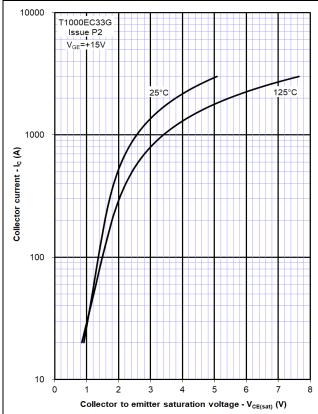
¹⁾

²⁾ 3)

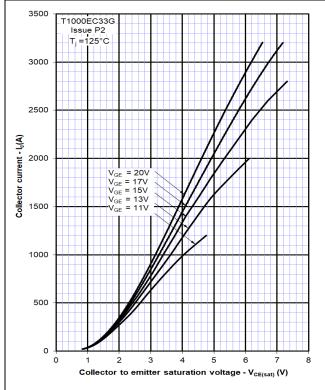


Curves









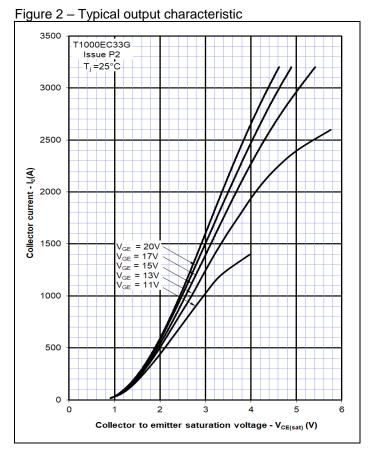


Figure 4 – Typical turn-on delay time vs gate resistance

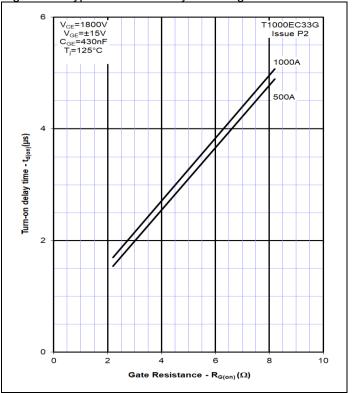
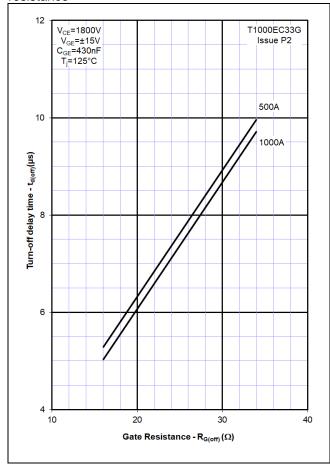
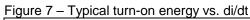
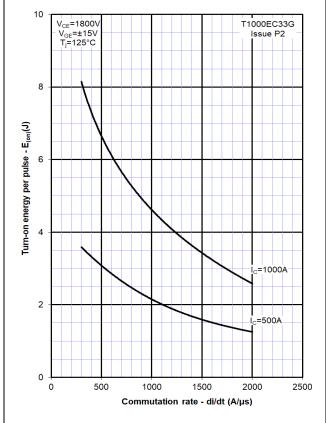


Figure 5 – Typical turn-off delay time vs. gate resistance









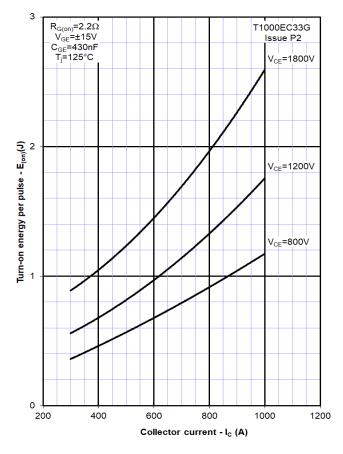
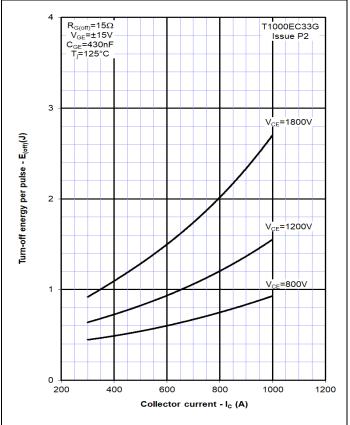


Figure 8 - Typical turn-off energy vs. collector current



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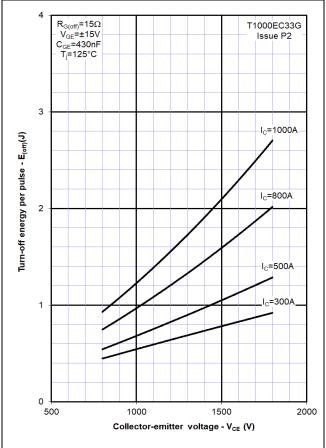
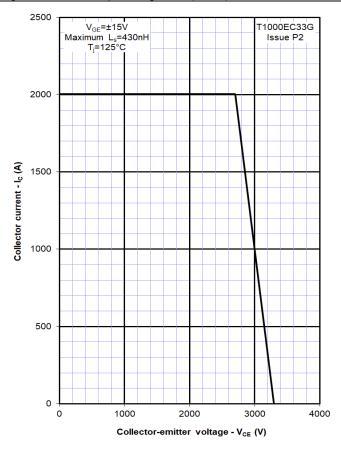
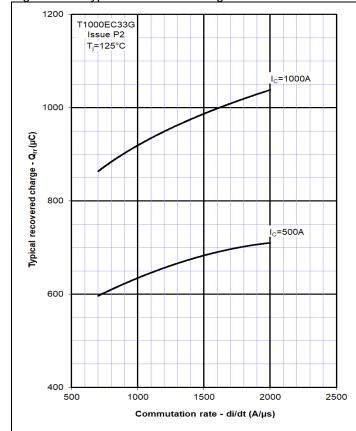


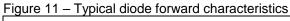
Figure 9 – Turn-off energy vs voltage

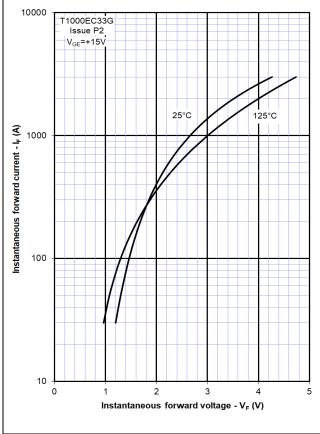
Figure 10 – Safe operating area (IGBT)













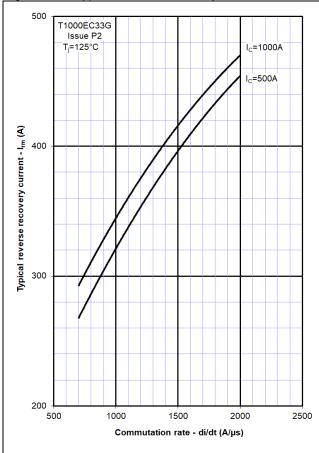


Figure 13 - Typical reverse recovery current

1.5

Figure 15 - Typical reverse recovery energy

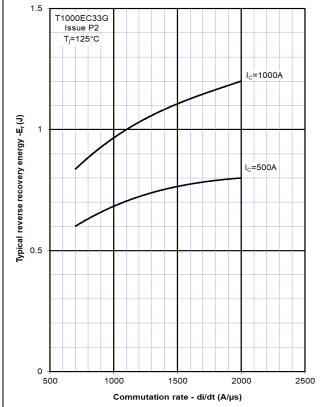


Figure 14 – Typical reverse recovery time

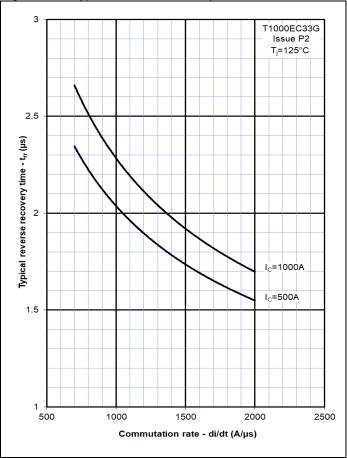
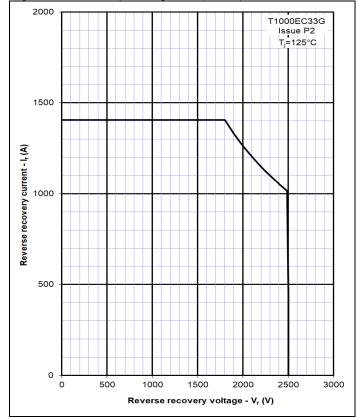


Figure 16 - Safe operating area (Diode)



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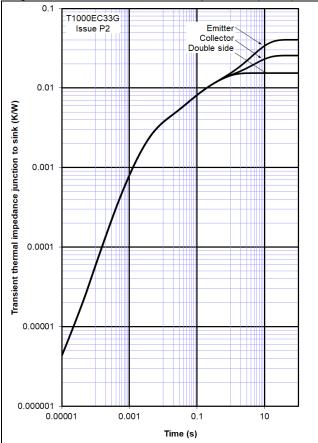
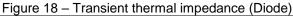
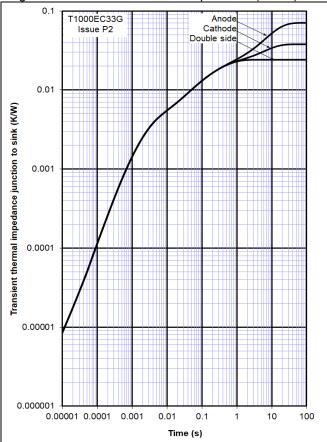
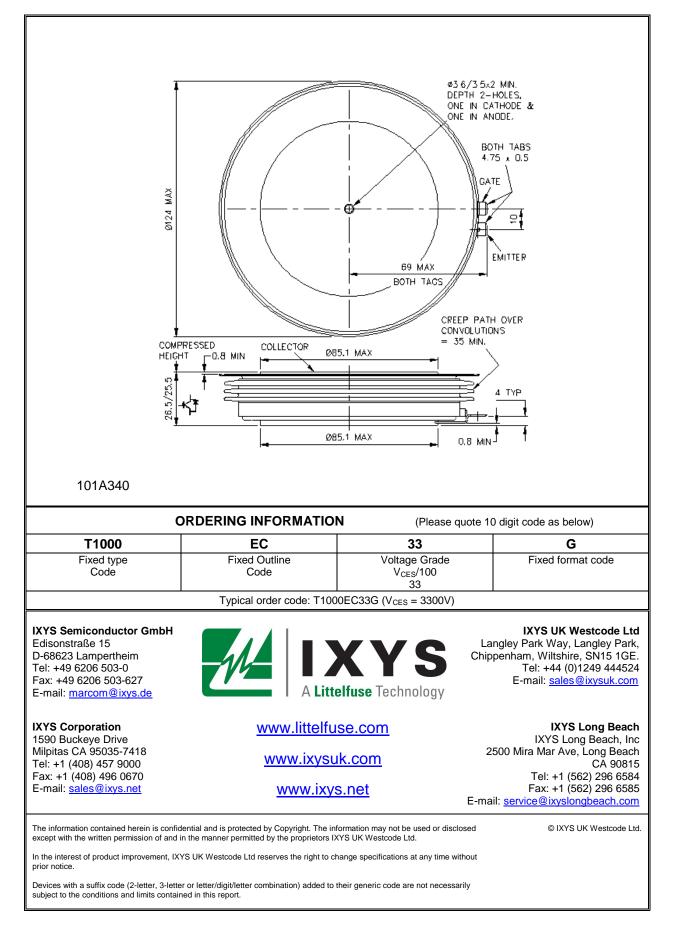


Figure 17 – Transient thermal impedance (IGBT)





Outline Drawing & Ordering Information





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